



IME-02-014

November 10, 2003

To: Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
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Subject:

Serial No. 10/638,235 08/08/03

Chaoyong Li et al.

METHOD TO FORM COPPER SEED LAYER
FOR COPPER INTERCONNECT

Grp. Art Unit: _____

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450, on November 21, 2003.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

 11/21/03

U.S. Patent Application Publication US 2002/0119657 A1 to Gandikota et al., "Method for Enhancing the Adhesion of Copper Deposited by Chemical Vapor Deposition," discloses a Cu process with a metal plasma CVD nucleation layer.

U.S. Patent Application Publication US 2002/0068449 A1 to Hashim et al., "Method of Depositing a Copper Seed Layer Which Promotes Improved Feature Surface Coverage," discloses a Cu seed layer process with a metal plasma CVD nucleation layer.

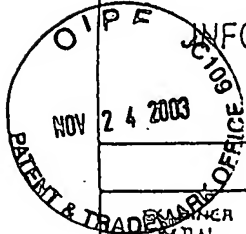
U.S. Patent 6,391,776 to Hashim et al., "Method of Depositing a Copper Seed Layer Which Promotes Improved Feature Surface Coverage," discloses a Cu seed layer process.

U.S. Patent 6,306,732 to Brown, "Method and Apparatus for Simultaneously Improving the Electromigration Reliability and Resistance of Damascene Vias Using a Controlled Diffusivity Barrier," discloses a Cu dual damascene process with a barrier layer.

Sincerely,



Stephen B. Ackerman,
Reg. No. 37761



Form PTO-1449	Document Number (Examiner) IME-02-014	Application Number 10/638,235
INFORMATION DISCLOSURE CITATION IN AN APPLICATION (Use several sheets if necessary)	Applicant Chaoyang Li et al.	
	Filing Date 08/08/03	Group Art Unit

U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	ALNO DATE IF APPROPRIATE
	6391776	5/2/02	Hashim et al.	438	687	1/5/01
	6306732	10/23/01	Brown	438	468	10/9/98

FOREIGN PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
					YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

-	U.S. Patent App. Pub. US 2002/0119657 A1 to Gandikota et. al., Pub. Date 8/29/02, Class 438/687, Filed 12/17/01.
-	U.S. Patent App. Pub. US 2002/0068449 A1 to Hashim et al., Pub. Date 6/6/02, Class 438/687, Filed 1/24/02.

EXAMINER	DATE CONSIDERED
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.